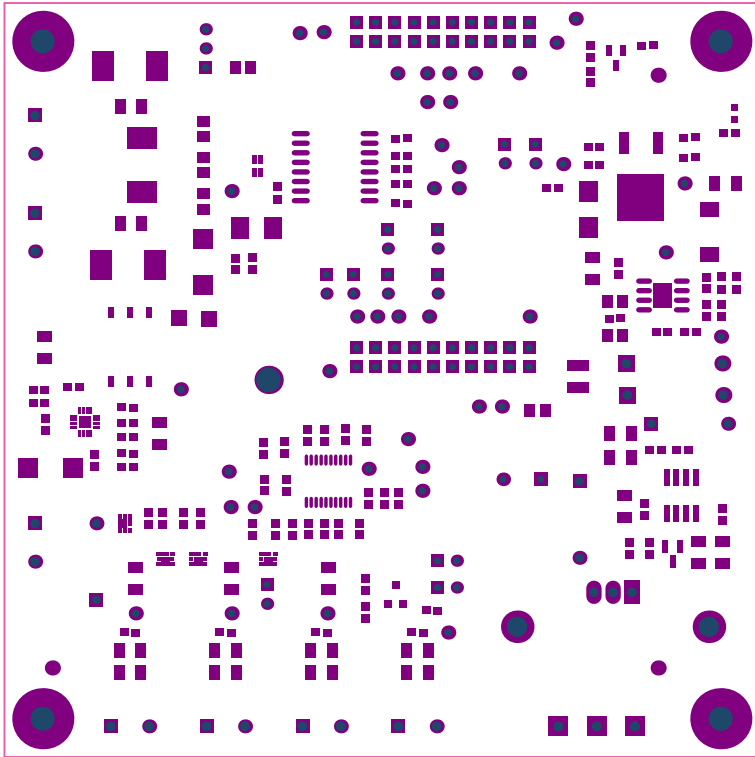
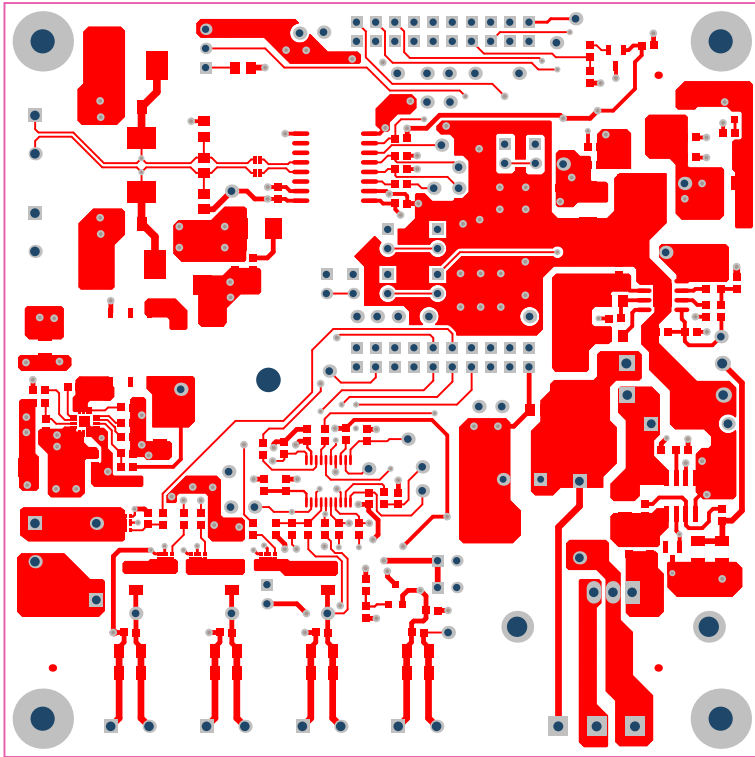


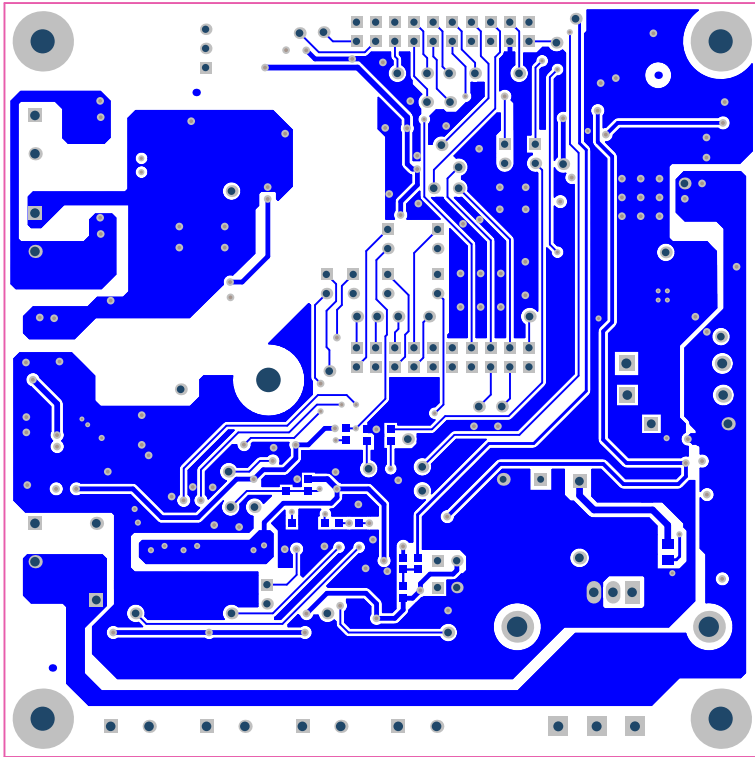
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Top Overlay	GENERATED : 2/21/2014	11:01:58 AM	TEXAS INSTRUMENTS



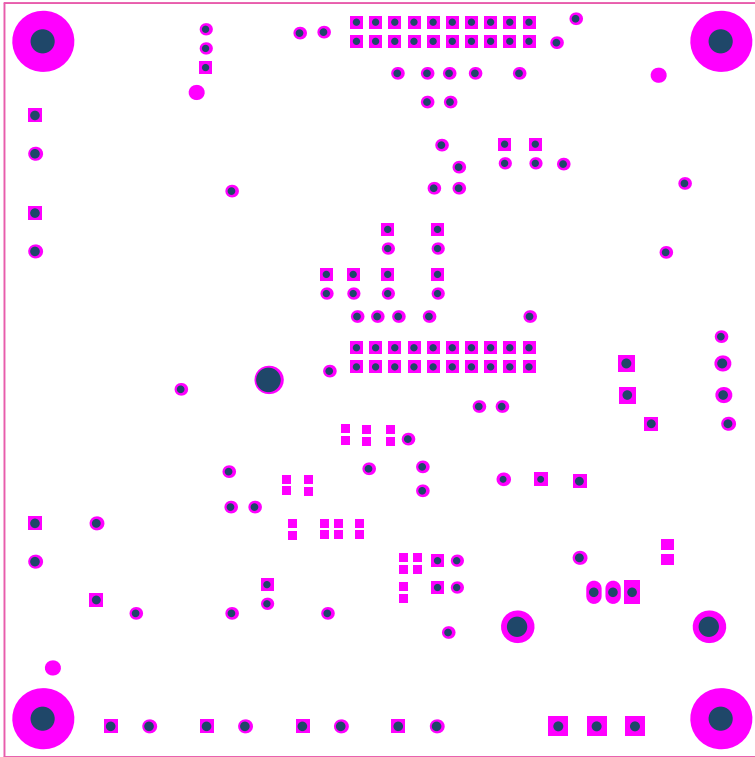
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Top Solder Mask	GENERATED : 2/21/2014 11:01:59 AM	TEXAS INSTRUMENTS	



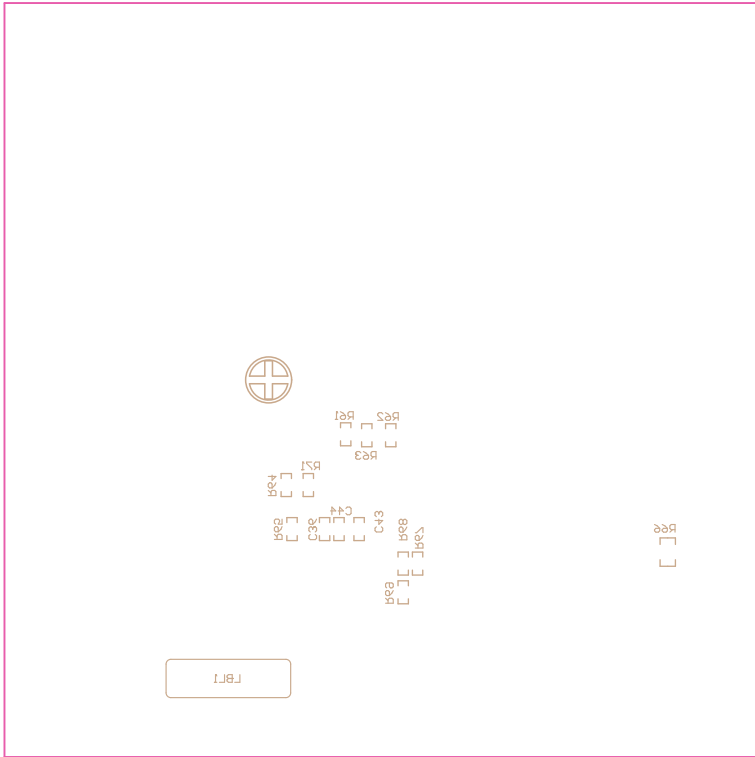
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TIDA-00130 P6A BASED MCCB-ETU		
PLOT NAME = Top Layer	GENERATED : 2/21/2014	11:01:59 AM	TEXAS INSTRUMENTS



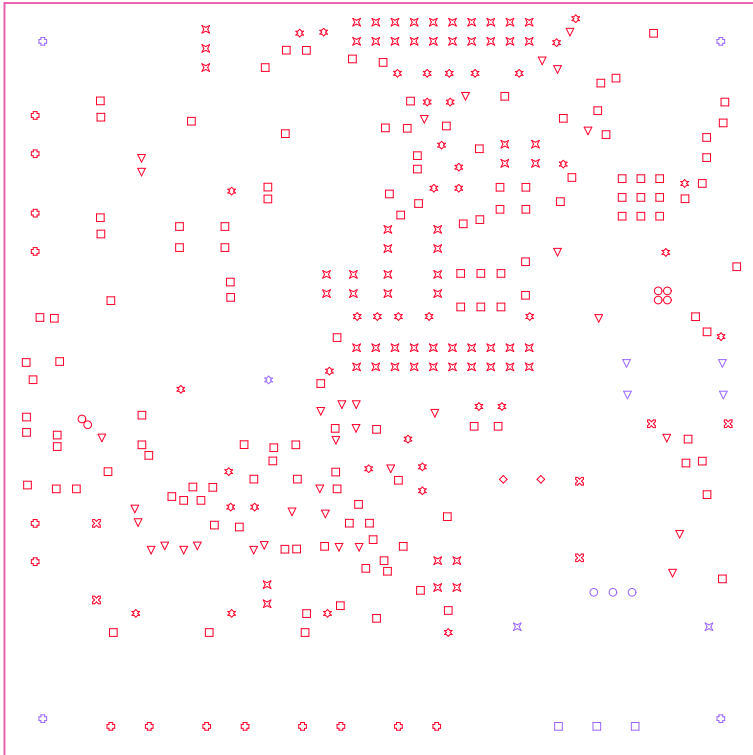
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Bottom Layer	GENERATED : 2/21/2014 11:02:00 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/21/2014 11:02:02 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Bottom Overlay	GENERATED : 2/21/2014	11:02:02 AM	TEXAS INSTRUMENTS

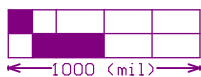
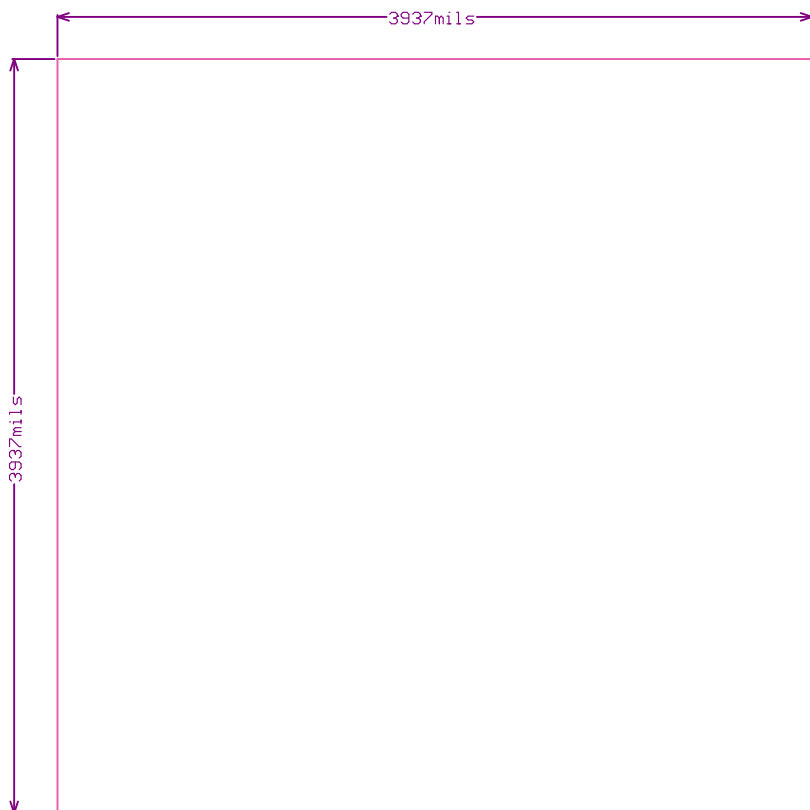


Symbol	Hit Count	Tool Size	Plated	Hole Type
○	6	12mil (0.305mm)	PTH	Round
▽	34	16mil (0.406mm)	PTH	Round
□	134	20mil (0.508mm)	PTH	Round
◇	2	36mil (0.914mm)	PTH	Round
×	65	38mil (0.965mm)	PTH	Round
☆	40	40mil (1.016mm)	PTH	Round
⊗	6	45.276mil (1.15mm)	PTH	Round
⊕	14	49.213mil (1.25mm)	PTH	Round
○	3	50mil (1.27mm)	PTH	Round
▽	4	51mil (1.295mm)	PTH	Round
□	3	52mil (1.321mm)	PTH	Round
×	2	106.5mil (2.705mm)	PTH	Round
⊕	4	125.984mil (3.2mm)	PTH	Round
☆	1	128mil (3.251mm)	NPTH	Round
318 Total				

Drill Table

DRILL TOLERANCES: FOR PTH +/-3MILS  
FOR NPTH +/-2MILS

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Drill Drawing	GENERATED : 2/21/2014	11:02:03 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00130	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TIDA-00130 PGA BASED MCCB-ETU		
PLOT NAME = Board Dimensions	GENERATED : 2/21/2014	11:02:04 AM	TEXAS INSTRUMENTS



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